



BR8 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 23.98%	Copper (Cu)	7440-50-8	1196.480	99.96	239,693.0
	Phosphorus (P)	7723-14-0	0.020	0.0016	3.9
	Arsenic (As)	7440-38-2	0.020	0.0016	3.9
	Tin (Sn)	7440-31-5	0.020	0.0016	3.9
	Oxygen (O)	7782-44-7	0.010	0.0008	2.0
	Sulfur (S)	7704-34-9	0.240	0.0200	48.0
	Iron (Fe)	7439-89-6	0.013	0.0011	2.6
	Nickel (Ni)	7440-02-0	0.006	0.0005	1.1
	Bismuth (Bi)	7440-69-9	0.040	0.0033	8.0
	Antimony (Sb)	1309-64-4	0.040	0.0033	8.0
	Lead (Pb)	7439-92-1	0.010	0.0008	2.0
	Zinc (Zn)	7440-66-6	0.006	0.0005	1.2
		Total		1,196.90	
Solder Wafer 0.31%	Lead (Pb)	7439-92-1	14.28	92.51	2,860.7
	Tin (Sn)	7440-31-5	0.77	4.99	154.3
	Silver (Ag)	7440-22-4	0.39	2.50	77.3
		Total		15.44	
Chip 0.32%	Silicon (Si)	7440-21-3	16.04	100.00	3,213.3
		Total		16.04	
Case 25.18%	Epoxy	25928-94-3	1,256.80	100.00	251,777.0
		Total		1,256.80	
Potting 50.04%	Epoxy	25928-94-3	2,497.70	100.00	500,368.7
		Total		2,497.70	
Plating 0.17%	Tin (Sn)	7440-31-5	8.84	100.00	1,770.9
		Total		8.84	
	Total mass (mg)		4991.72		